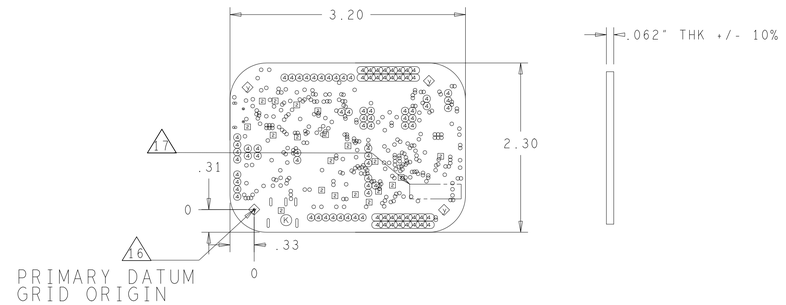
REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE	07-24-15	J.S.
	B	RESPIN PER ECO62934	02-08-16	A.J.
	B1	UPDATE BOARD PART NUMBER SILK	03-10-16	A.J.

NOTES (UNLESS OTHERWISE SPECIFIED):

1. THIS DRAWING SPECIFIES THE REQUIREMENTS FOR A PRINTED WIRING BOARD IN ACCORDANCE WITH SPECIFICATION IPC-A-600 CLASS 2 (LATEST REVISION).
2. THE PWB MUST BE LEAD FREE ASSEMBLY PROCESS COMPATIBLE AND MUST BE ABLE TO HANDLE A MINIMUM OF 5 CYCLES AT 260 DEGREES CELSIUS FOR 10 SECONDS.
3. BASE MATERIAL - LAMINATE AND PREPREG SHALL MEET IPC-4101B-26, 83 or 98
   Tg - MUST BE GREATER THAN OR EQUAL TO 150 DEGREES CELSIUS.
   Td - MUST BE GREATER THAN OR EQUAL TO 330 DEGREES CELSIUS.
4. COPPER FOIL WEIGHT - SEE STACKUP DETAIL 'A'
5. CHARACTERISTIC IMPEDANCE - SEE DETAIL 'B'
6. MINIMUM CONDUCTIVE WIDTH/SPACING TO BE .0057"/.005"
7. PLATING FINISH - BOTH SIDES ENIG (ELECTROLESS NICKEL IMMERSION GOLD):
   .05080-.232 MICRON (2-8 MICROINCH) OF GOLD OVER
   2.540-6.350 MICRON (100-250 MICROINCH) OF NICKEL.
8. ALL THROUGH HOLE VIAS MAY BE PLATED SHUT.
9. SOLDERMASK - BLUE COLOR (TAIYO OR EQUIVALENT), BOTH SIDES.
   MODIFICATION OF SOLDERMASK IS NOT ALLOWED WITHOUT WRITTEN PERMISSION FROM NXP.
10. SILKSCREEN - WHITE EPOXY INK, BOTH SIDES. NO SILK ON PADS.
11. ELECTRICAL TEST - 100% IPCD356.
12. PRINTED WIRING BOARD IS TO BE INDIVIDUALLY BAGGED.
13. DRC'S MUST BE RUN ON THE GERBER BEFORE BUILDING BOARDS, UNLESS PRIOR APPROVAL IS GIVEN IN WRITING BY NXP.
14. TEARDROPS MAYBE ADDED AT THE FAB HOUSE TO ALL SIGNAL LAYERS.
15. TWO SOLDER SAMPLES TO BE PROVIDED.
16. BASIC GRID INCREMENT AT 1:1 IS .0001.
17. SUPPLIER MARKINGS - ON SOLDER SIDE ONLY, WHERE SHOWN.
    - MUST BE UL RECOGNIZED AND MUST HAVE AN ID THAT CONFORMS TO UL94V-0
18. THE PWB WILL BE MARKED AS LEAD FREE BY USE OF AN INK STAMP (PB)
19. THE PWB WILL BE MARKED AS LEAD FREE PROCESS COMPATIBLE BY USE OF AN INK STAMP (260°C)
20. ALL PLATED AND NON-PLATED THROUGH HOLES ARE TO BE DRILLED AT PRIMARY DRILL STEP. ALL HOLE LOCATION TOLERANCES ARE TO BE +/-.002 IN REFERENCE TO THE PRIMARY DATUM.
21. FINISHED PCB MUST BE PANELIZED FOR ASSEMBLY ACCORDING TO CONTRACT MANUFACTURERS REQUIREMENTS. THE ADDITION OF RAILS AND .125"NON-PLATED TOOLING HOLES ARE AT THE DISCRETION OF CONTRACT MANUFACTURER.PANELIZATION MUST BE APPROVED BY CONTRACT MANUFACTURER.
22. THE MANUFACTURE HAS THE OPTION TO ADD COPPER THIEVING ON OUTER AND INNER LAYERS, KEEP A MINIMUM DISTANCE OF .100" FROM ANY BOARD FEATURES.
23. INTENTIONAL 5 SHORTS AT:

Location	RefDes	Net 1		Net 2
(1063.50 1597.00)	SH2	OSBDM_RXD	&	PT4
(879.50 1597.00)	SH1	OSBDM_TXD	&	PT5
(2340.51 306.41)	SH8	N16959068	&	PP3
(2441.28 123.27)	SH6	N16959058	&	PP1
(2439.22 422.34)	SH7	N16959074	&	PP5



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
○	10.0	+0.0/-10.0	PLATED	299
⊡	24.0	+2.0/-2.0	PLATED	20
⊕	40.0	+3.0/-3.0	PLATED	58
⊕	47.0	+3.0/-3.0	PLATED	32
⊗	100.0	+2.0/-2.0	NON-PLATED	1
◇	125.0	+2.0/-2.0	NON-PLATED	4
▭	34.0x30.0	+2.0/-2.0	PLATED	2
⬭	59.0x33.0	+2.0/-2.0	PLATED	2
▯	111.0x32.0	+2.0/-2.0	PLATED	3
▯	122.0x32.0	+2.0/-2.0	PLATED	2

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DETAIL B
IMPEDANCE REQUIREMENTS
IMPEDANCE TOLERANCE IS 10%

Layers	Single Ended		Differential		
	Trace Width (Mils)	Impedance (Ohms)	Trace Width (Mils)	Trace Spacing "Airgap" (Mils)	Impedance (Ohms)
L1_PS	6.30	50	5.70	6.00	90
L4_SS	6.30	50	5.70	6.00	90

FINISHED Cu WEIGHT

LAYER 1	COMPONENT SIDE	1/2 oz.
LAYER 2	GROUND PLANE	1 oz.
LAYER 3	POWER PLANE	1 oz.
LAYER 4	SOLDER SIDE	1/2 oz.

DETAIL A
LAYER STACKUP
SCALE: NONE

___ COMPANY PUBLIC
_X_ COMPANY INTERNAL
___ COMPANY CONFIDENTIAL

PART NO. 170-28891

THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO NXP AND SHALL NOT BE USED FOR ENGINEERING DESIGN PROCUREMENT OR MANUFACTURE IN WHOLE OR IN PART WITHOUT THE CONSENT OF NXP.

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
DECIMALS .XX ±.01 .XXX ±.005
ANGLES ±0°30'
√ RMS ALL MACHINED SURFACES
BREAK ALL SHARP EDGES AND CORNERS.
REMOVE BURRS.
UNDERLINED DIM. NOT TO SCALE.
THIRD ANGLE ORTHOGRAPHIC PROJECTION IS USED.

APPROVALS	DATE
DRAWN MARIO VELASCO	03-10-16
CHECKED ALFREDO ALVAREZ	03-10-16
DESIGN ENGINEER M.A JIMENEZ	03-10-16

NXP SEMICONDUCTORS
6501 WILLIAM CANNON DRIVE WEST AUSTIN, TEXAS 78735 USA

TITLE: PRINTED WIRING BOARD
DEVKIT-S12ZVL

SIZE	CAD FILE NAME	DWG. NO.	REV
D	LAY-28891	FAB-28891	B1

SCALE 1/1 DO NOT SCALE DRAWING SHEET 1 OF 1